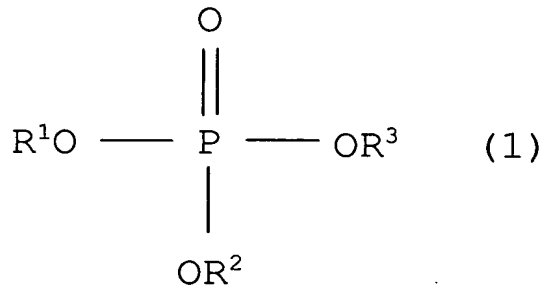
CLAIMS

1. An inorganic powder-containing resin composition comprising inorganic powder, a binder resin, and a phosphorus compound represented by formula (1):



(1)

wherein R^1, R^2 and R^3 independently represent H, an alkyl group, an alkylaryl group, NH_4^+ (ammonium) or $-(CH_2CH_2O)_n-R^4$, wherein n is 1 to 15, and R^4 represents H, an alkyl group, an alkylaryl group or a (meth)acryloyl group.

2. The inorganic powder-containing resin composition according to claim 1, wherein the weight-average molecular weight of the binder resin is 50,000 to 500,000.

3. The inorganic powder-containing resin composition according to claim 1 or 2, wherein the binder resin is (meth)acrylic resin.

4. The inorganic powder-containing resin composition according to claim 3, wherein the (meth)acrylic resin has a carboxyl group.

5. The inorganic powder-containing resin composition according to claim 4, wherein the (meth)acrylic resin has an acid

value of 0.5 to 5 KOH mg/g.

6. The inorganic powder-containing resin composition according to claim 1 to 5, wherein 5 to 50 parts by weight of the binder resin and 0.1 to 10 parts by weight of the phosphorus compound relative to 100 parts by weight of the inorganic powder are contained.

7. The inorganic powder-containing resin composition according to claim 1 to 6, wherein the inorganic powder is glass powder.

8. The inorganic powder-containing resin composition according to claim 1 to 7, wherein the viscosity of the inorganic powder at 600°C is 150 Pa·s or less.

9. The inorganic powder-containing resin composition according to claim 1 to 8, which is used as a material forming a dielectric layer.

10. A film-forming material layer comprising the inorganic powder-containing resin composition according to claim 1 to 9 formed in a sheet form.

11. A transfer sheet comprising at least the film-forming material layer according to claim 10 laminated on a support film.

12. A dielectric layer comprising the film-forming material layer according to claim 10 sintered therein.

13. A method of producing a substrate having a dielectric layer formed thereon, comprising the step of transferring the film-forming material layer of the transfer sheet according to claim 11 onto a substrate and the step of sintering the transferred film-forming material layer at 550 to 650°C to form a dielectric layer on the substrate.

14. A substrate having a dielectric layer formed thereon, which is produced according to the method of claim 13.